

**LEGEND**

C Customers by Region  
 AS=Asia (except Japan); EU=Europe;  
 JP=Japan; NA=North America;  
 ROW=Rest of World

Quality Audits  
 A=ISO-9001; B=ISO-9002; C=ISO-14000;  
 D=SAC Level 1; E=OS9000; F=Other (specify)

Technologies  
 EL=Electroless; EP=Electroplating;  
 EV=Evaporation; SC=Screening; O=Other

Bump Alloys/Metals  
 63-63/37; HL=High Lead;  
 LA=Low Alpha; NL=No Lead;  
 Au=Gold; O=Other (specify)

Company Address	Phone	Fax	Chairman	President	CEO	COO	Other Title	Year Founded	Customers by Region (%)	Quality Audits	Manufacturing Area in Meters <sup>2</sup>	Technologies	Bump Alloys/Metals	Water Size Maximum (in mm)	Max. No. of Bumps per Wafer	* Bump Pitches Offered (in microns)	2 Waters per Month Capacity	Steppers (S), Aligners (A)	Web Site	Customer Contact	Phone	Fax	Additional Offices
<b>Advanced Semiconductor Engineering Inc.</b> Rm 1901, TWTC Intl. Trade Bldg., No. 333 Keelung Rd., Sec. 1, Taipei 110, Taiwan ROC	+886.2.87805489	+886.2.2757612	Jason Chang	Richard Chang				1984	AS=38, EU=7, JP=1, NA=54	B, C, D, E	CM	EP, SC	63, HL, LA, NL	150-300	5,500	100	10K plated, 50K SC	S, A	aseglobal.com	Jennifer Yuen, marketing@aseus.com	408.986.6500	408.565.0289	ASE (U.S.) Inc. (see web site listings)
<b>Advanpack Solutions Pte. Ltd.</b> c/o Advanced Systems Automation Ltd. 54 Serangoon North Ave. 4, Singapore 555854	(65)483.7235	(65)483.7237	Chan Kok Pun	Jimmy Chew	Yew Ah Ming (CFO)			1996	AS=5, EU=40, JP=2, NA=48, ROW=5	A	712.7	EP	63, HL, LA, NL, Au, O*	125-200	Die design dependant	80	>4,000	S, A	advanpack.com	Winston Koh, winston.koh@advanpack.com	(65)6550.3231	(65)6555.5838	No. 2 Woodlands Sector 1, #05-33, Woodlands Spectrum, Singapore 738068 *O=Copper pillar bump
<b>Amkor Technology</b> 1900 S. Price Road Chandler, AZ 85248	480.821.5000	480.821.6937	James Kim	John Boruch				1968	5,000+	A, B, C, D, E	EP, SC	EP, SC	63, HL, LA, ON/A	200	~475,000	125, 200, 225	12,000	A	amkor.com	Consult manufacturer			
<b>APTOS Corporation</b> 1557 Centre Pointe Dr. Milpitas, CA 95035	408.956.7988	408.956.7979	C.S. Ho					1985	EL=10, NA=90	B	N/A	EL, EP	63, HL, LA, O	200	Au: 50, Solder: 200	12,000	A	aptoscorp.com	John Lee, jlee@aptoscorp.com	408.941.2474	408.956.7979		
<b>APTOS Taiwan Corporation</b> No. 3 Industry East Road III Science-Based Industrial Park Hsin-Chun 300, Taiwan, ROC	+886.3.5631079	+886.3.5641269	C.S. Ho	Richard Haug				1985	AS=60, EU=5, JP=35	B	1,000	EP	Au	125, 150, 200	30	25,000	S, A	aptos.com.tw	John Lee, APTOS Corporation, Sales and Marketing Executive, jlee@aptoscorp.com	408.941.2474	408.956.7979	James Chen, james_chen@aptos.com.tw	
<b>Chipbond Technology Corporation</b> 1-6, Li-Hsin 1 Rd. Science-Based Industrial Park Hsin-Chu, Taiwan	+886.3.5678788	+886.3.5638998	Dr. Chunghsin Lee	Fei-Jain Wu, David Cheng				1997	AS=40, EU=20, JP=40, NA=20	B, C, E	23,000	EP	63, HL, LA, Au	100-200	No limit	Au: 32, Solder: 100	70,000	S, A	chipbond.com.tw	Burt Yiu, byiu@chipbond.com.tw	+886.3.5678788	+886.3.5788003	
<b>Fujitsu</b> Marunouchi Bldg. Tokyo, Japan	+81.3.3216.3211		Tadashi Sekizawa	Naooyuki Akikusa	Takashi Takaya (CFO)			1935	AS=10, JP=40, NA=50	A, B, C	CM	EL, EP, SC	63, HL, LA, NL, Au	150-200	2,000,000	150	11,000	S, A	fma.fujitsu.com	Debbie Scrivens, dscriven@fma.fujitsu.com	408.737.5745	408.737.5981	1250 E. Arques Ave., M/S 333, P.O. Box 3470, Sunnyvale, CA 94088
<b>FuPo Electronics Corp.</b> 3F, #2-1, Li-Hsin Rd., HSIP Hsinchu, Taiwan	+886.3.5799339	+886.3.5630331	J.J. Wu	Eric Cheng	Kevin Chang			1997	AS=100	A, C	550	EP	63, Au	150-200	420,000	40	20,000	S	fupo.com.tw	H.S. Wen, hs_wen@fupo.com.tw	+886.3.5799339 ext. 3000	+886.3.5644451	

